

ABSTRACT OF THE DISCLOSURE

A chuck system for supporting a semiconductor wafer that includes a chuck platform for supporting the semiconductor wafer, and a lift structure movably coupled with the chuck platform to receive the semiconductor wafer that includes a lift base, and at least one lift pin removably coupled with the lift base, the lift pin having two ends with a first end removably coupled to the lift base and a second end for supporting the semiconductor wafer during lifting operation of the lift structure.

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09802924-031004
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